



Product Change Notification: BLAS-18QUNE687

Date:

23-Feb-2026

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors

Notification Subject:

CCB 8095 Final Notice: Qualification of CuPdAu as a new bond wire material for selected AT42QT18C15, AT42QT5480, AT89LP3240, AT89LP51, AT89LP51ED2, AT89LP51IC2, AT89LP51ID2, AT89LP51RB2, AT89LP51RC2, AT89LP51RD2, AT89LP52, AT89LP6440, ATmega1284, ATmega1284P, ATmega16, ATMEGA162, ATmega164A, ATmega164P, ATmega164PA, ATmega16A, ATmega32, ATmega324A, ATmega324P, ATMEGA324PA, ATmega32A, ATmega644, ATmega644A, ATmega644P, ATmega644PA, ATmega8515 and ATmega8535 device families available in 44L VQFN (7x7x1mm) package assembled at MMT site.

Affected CPNs:

[BLAS-18QUNE687_Affected_CPN_02232026.pdf](#)

[BLAS-18QUNE687_Affected_CPN_02232026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CuPdAu as a new bond wire material for selected AT42QT18C15, AT42QT5480, AT89LP3240, AT89LP51, AT89LP51ED2, AT89LP51IC2, AT89LP51ID2, AT89LP51RB2, AT89LP51RC2, AT89LP51RD2, AT89LP52, AT89LP6440, ATmega1284, ATmega1284P, ATmega16, ATMEGA162, ATmega164A, ATmega164P, ATmega164PA, ATmega16A, ATmega32, ATmega324A, ATmega324P, ATMEGA324PA, ATmega32A, ATmega644, ATmega644A, ATmega644P, ATmega644PA, ATmega8515 and ATmega8535 device families available in 44L VQFN (7x7x1mm) package assembled at MMT site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	C194	C194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 13 April 2026 (date code: 2616)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2026				>	April 2026				
Work Week	06	07	08	09		14	15	16	17	18
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated Implementation Date								X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 23, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_BLAS-18QUNE687_Qualification Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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